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Semiconductor devices –

Part 16-10: Technology Approval Schedule (TAS) for monolithic microwave integrated circuits

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –

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FOREWORD

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International Standard IEC 60747-16-10 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47E/257/FDIS	47E/262/RVD



Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

The QC number that appears on the front cover of this publication is the specification number in the IEC Quality Assessment System for Electronic Components (IECQ-CECC).

This publication has been partially drafted in accordance with the ISO/IEC Directives, Part 2 (2001). It also follows the requirements given in IEC QC 210000:1995, Technology Approval Schedules – Requirements under the IEC Quality Assessment System for Electronic Components (IECQ-CECC).

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

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Foreword to this particular Technology Approval Schedule (TAS)

The IEC Quality Assessment System for Electronic Components (IECQ) is composed of those member countries of the International Electrotechnical Commission (IEC) that wish to take part in a harmonized system for electronic components of assessed quality.

The object of the System is to facilitate international trade by the harmonization of specifications and quality assessment procedures for electronic components and by the granting of an internationally recognized mark or certificate of conformity. The components produced under the System are acceptable in all member countries without further testing.

This TAS has been prepared for use by those countries taking part in the System who wish to issue national harmonized specifications for Technology Approval of manufacturers of monolithic microwave integrated circuits. It should be read in conjunction with the current regulations of the IECQ-CECC System.

At the date of printing of this schedule the member countries of IECQ-CECC are China, Denmark, France, Germany, India, Italy, Japan, Republic of Korea, Netherlands, Norway, Russian Federation, Switzerland, Thailand, Ukraine, United Kingdom, USA and Yugoslavia. Copies of this schedule can be obtained from their National Authorized Institutions, National Standards Organizations or, in case of difficulty, from the Central Office of IEC in Geneva, Switzerland (fax 41 22 9190300) as described in the Specifications List QC 001004 on www.iecq-cecc.org.

Organizations responsible for preparing the present TAS

IEC subcommittee 47E: Discrete semiconductor devices

Preface

This schedule was prepared by SC47E/WG2.

It is based, wherever possible, on the publications of the International Electrotechnical Commission (IEC) and the International Organization for Standardization (ISO) and in particular on:

- IEC 60747-16-1: Semiconductor devices – Part 16-1: Microwave integrated circuits – Amplifiers,
- IEC 60747-16-2: Semiconductor devices – Part 16-2: Microwave integrated circuits – Frequency prescalers,
- IEC 60747-16-3: Semiconductor devices – Part 16-3: Microwave integrated circuits – Frequency converters,
- IEC 60747-16-4: Semiconductor devices – Part 16-4: Microwave integrated circuits – Switches.

INTRODUCTION

The requirements for Technology Approval for manufacturers of electronic and electro-mechanical components are given in QC 001002-3, Clause 6. The procedures for approval defined in that clause require the manufacturer to have available an appropriate Technology Approval Schedule (TAS).

This schedule defines how the principles and requirements of QC 001002-3, Clause 6 are applied to monolithic microwave integrated circuits.

SEMICONDUCTOR DEVICES –

Part 16-10: Technology Approval Schedule (TAS) for monolithic microwave integrated circuits

1 General

1.1 Scope

This TAS specifies the terms, definitions, symbols, quality system, test, assessment and verification methods and other requirements relevant to the design, manufacture and supply of monolithic microwave integrated circuits in compliance with the general requirements of the IECQ-CECC System for electronic components of assessed quality.

1.2 Normative documents

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60027 (all parts): *Letter symbols to be used in electrical technology*

IEC 60050: *International Electrotechnical Vocabulary*

IEC 60068 (all parts): *Environmental testing*

IEC 60191-2: *Mechanical standardisation of semiconductor devices – Part 2: Dimensions*

IEC 60617-DB¹ (all parts): *Graphical symbols for diagrams*

IEC 60747-1: *Semiconductor devices – Discrete devices and integrated circuits – Part 1: General*

IEC 60747-16-1: *Semiconductor devices – Part 16-1: Microwave integrated circuits – Amplifiers*

IEC 60747-16-2: *Semiconductor devices – Part 16-2: Microwave integrated circuits – Frequency prescalers*

IEC 60747-16-3: *Semiconductor devices – Part 16-3: Microwave integrated circuits – Frequency converters*

IEC 60747-16-4: *Semiconductor devices – Part 16-4: Microwave integrated circuits – Switches²*

IEC 60748-1: *Semiconductor devices – Integrated circuits – Part 1: General*

ISO 1000: *SI units and recommendations for the use of their multiples and certain other units*

¹ "DB" refers to the IEC on-line database.

² To be published.